

Highly efficient reflection package for proximity sensor

Package AAM11 Series for IR LED Module

New



Individual piece (cut shape)

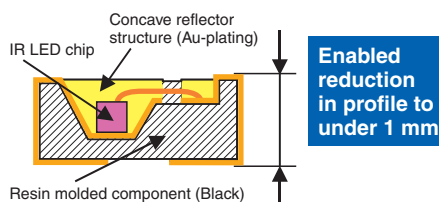
RoHS compliant

FEATURES

1. Realization of small, low-profile reflector package through application of our unique MID* technology (MIPTEC)

Individual piece: $2.3 \times 1.95 \times 0.9$ mm

<Cross section of package>

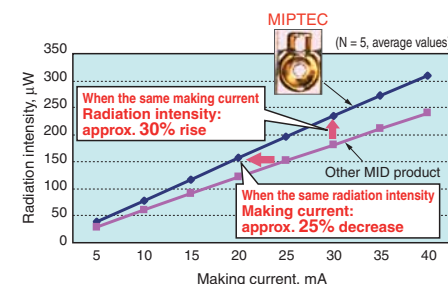


Note: LED chip to be prepared and mounted separately by the customer.

* MID (Molded Interconnect Devices): Molded components with an electrical circuit formed on 3D surfaces.

2. A concave reflector structure with good directivity and increased light extraction efficiency due to bright plating specifications contributes to decreased module power consumption

* The graph below uses typical values, and details will vary according to the LED chip specifications.



APPLICATIONS

1. Light projection type Inductive proximity sensor package
 - Smartphone display control
 - Finder control of single-lens reflex
2. IR LED lighting for surveillance camera

ORDERING INFORMATION

AAM 1 1 0 1 0 6

Molding material/Size of sheet
1: PPA (Black)
50 × 70 mm

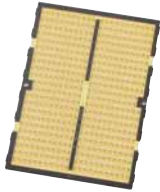
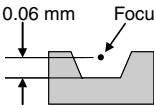
Unit size (2 digits)
01: $2.3 \times 1.95 \times 0.9$ mm

Focal length (2 digits)
06: 0.06 mm*

Au-plating thickness
1: 0.1 ± 0.05 μm
2: 0.2 ± 0.1 μm
3: 0.3 ± 0.1 μm

* For requests of products with different focal lengths, please contact our sales office.

PRODUCT TYPES

Appearance of sheet	Material of molding sheet	Appearance of individual piece	Focal length	Au-plating thickness (μm)	Part number (Delivered in sheet form)	Packing (one carton)
 50 × 70 mm	Polyphthalamide (PPA) Black	 2.3 × 1.95 mm h = 0.9 mm (436 pieces/sheet)	 0.06 mm Focus Distance from the bottom surface of the mounted LED chip to the focal section	0.1±0.05	AAM1101061	6 trays (Contains 432 sheets)
				0.2±0.1	AAM1101062	
				0.3±0.1	AAM1101063	

Notes: 1. This product is delivered in sheet form, and customers are required to mount the LED chips and cut the sheet into individual pieces.
2. For requests of focal lengths other than those mentioned above, please contact our sales office.
3. For requests of evaluation samples, please contact our sales office.

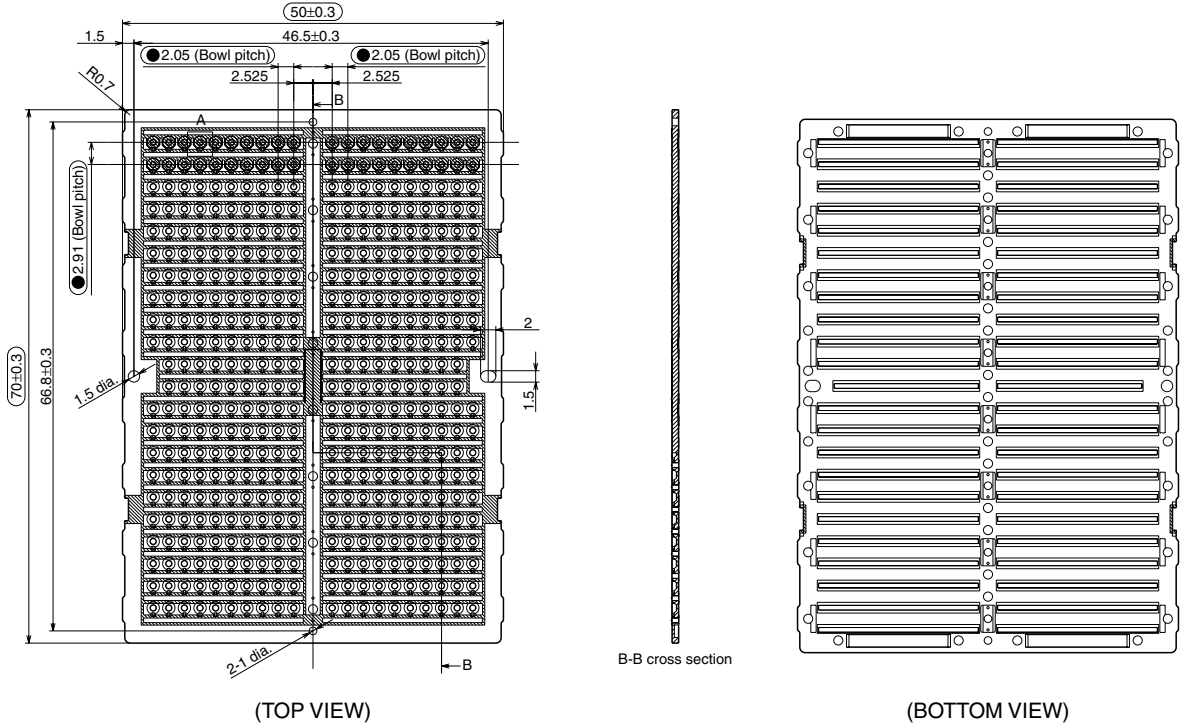
SPECIFICATIONS

Product specifications (Measurement conditions: 25±3°C unless stated otherwise)

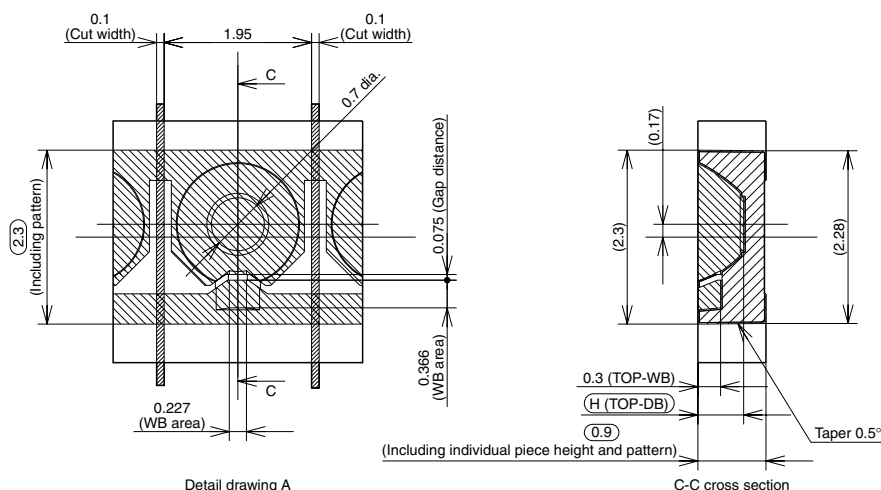
Item		Specifications
Plating thickness	Cu-plating	13±7 μm
	Ni-plating	6±4 μm
	Au-plating	0.1±0.05 μm (AAM1101061) 0.2±0.1 μm (AAM1101062) 0.3±0.1 μm (AAM1101063)
	Total thickness	19±11 μm
Plating adhesion strength (Measurement area refer to product drawing)		0.39 N/m or higher (initial) Measured after Au-plating
Ambient environment (No freezing and no dew condensation)	Temperature	−20°C to 50°C Maximum temperature when applying an electrical current: 85°C
	Humidity	15% to 85%RH
	Pressure	86 kPa to 106 kPa

DIMENSIONS (Unit: mm)

1. Sheet dimensions (Delivered form)



2. Individual piece (cut shape)



General tolerance: ± 0.1

NOTES

1. Handling during storage

1) Although the outermost surface is coated in Au-plating, if exposed to atmospheres containing corrosive gases, humidity or at high temperature, the underlying nickel or copper may corrode causing discoloration of the plated surface, decreasing reflectance, and this may lead to decreased mountability or joint reliability of LED components or soldering. Therefore, please pay close attention to the atmosphere used for storage.

2) Storage conditions ("After opening" refers to after opening the packing bag)

The following conditions must be followed in order to maintain plating adhesive strength and external performance.

	Before opening	After opening
Temperature	15°C to 35°C	23°C $\pm$ 3°C
Humidity	RH25% to 75%	RH50% or less
Pressure	86 kPa to 106 kPa	86 kPa to 106 kPa
Storage life (*2)	3 months	1 month (*1)

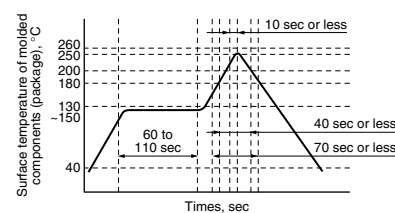
*1: Please keep it in desiccator set into the clean room.

*2: The storage life means the length from the date (lot number) printed on packaging.

2. Soldering

Please use the reflow temperature profile conditions recommended below for reflow soldering. Please contact us before using a temperature profile other than that described below.

Recommended soldering temperature conditions



Please contact

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